

# N-Channel 60 V (D-S) MOSFET

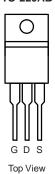
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0035			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0090			
I <sub>D</sub> (A)	210			
Configuration	Single			

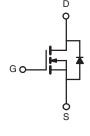
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		$V_{DS}$	60	V		
Gate-Source Voltage		V <sub>GS</sub> ± 20		¬		
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	210			
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	120 <sup>a</sup>			
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	120 <sup>a</sup>	Α		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	480			
Single Pulse Avalanche Current	L = 0.1 mH	l <sub>AS</sub>	75			
Single Pulse Avalanche Energy	L = U. I IIII	E <sub>AS</sub>	281	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	375	W		
	T <sub>C</sub> = 125 °C	$P_{D}$	125	VV		
Operating Junction and Storage Temperature Range	ge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	40	°C/W	
Junction-to-Case (Drain)		$R_{thJC}$	0.4	C/ VV	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	1			ı				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		60	-	-	.,	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0	-	3.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1.0		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μA	
-		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	350		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	V <sub>DS</sub> ≥ 5 V	120	-	-	Α	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.0035	-	Ω	
Dunin Course On Chata Basistanas		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	0.0060	-		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	0.0080	-		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A	-	0.0090	-		
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	109	-	S	
Dynamic <sup>b</sup>								
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	8600	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	1000	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	750	-		
Total Gate Charge <sup>c</sup>	Qg			-	180	-		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 110 \text{ A}$	-	24.7	-	nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		-	50.4	-		
Gate Resistance	$R_g$	f = 1 MHz		0.5	1.1	1.6	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_L = 0.27 \Omega$ $I_D \cong 110 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$		-	19	29	ns ns	
Rise Time <sup>c</sup>	t <sub>r</sub>			-	23	35		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	83	125		
Fall Time <sup>c</sup>	t <sub>f</sub>			-	35	53		
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>	•						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0		-	0.9	1.5	V	

#### Notes

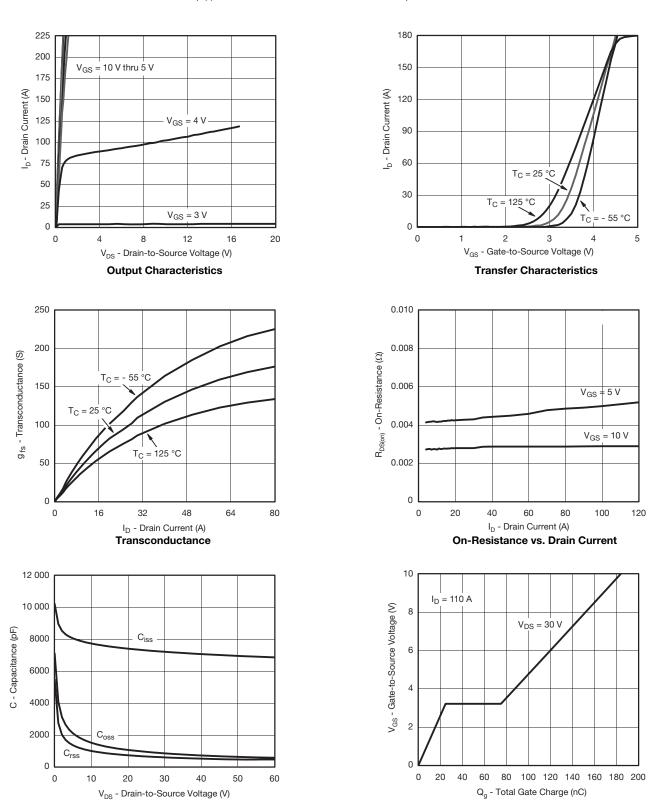
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

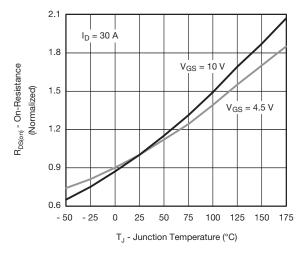
Capacitance

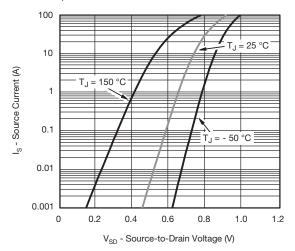


**Gate Charge** 

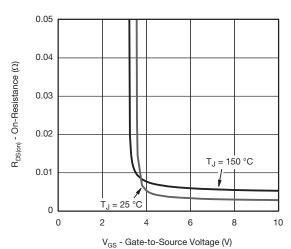


## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)

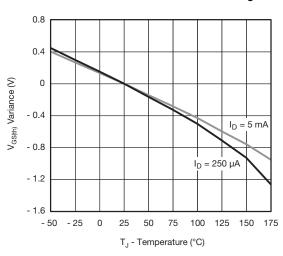




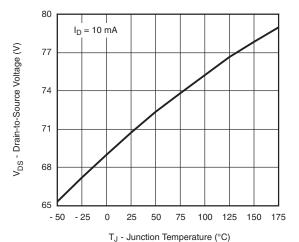
#### On-Resistance vs. Junction Temperature



**Source Drain Diode Forward Voltage** 



#### On-Resistance vs. Gate-to-Source Voltage

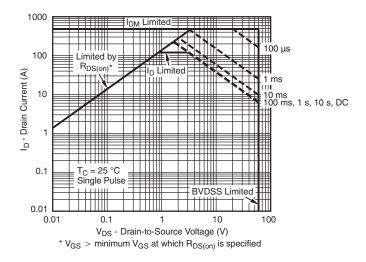


#### Threshold Voltage

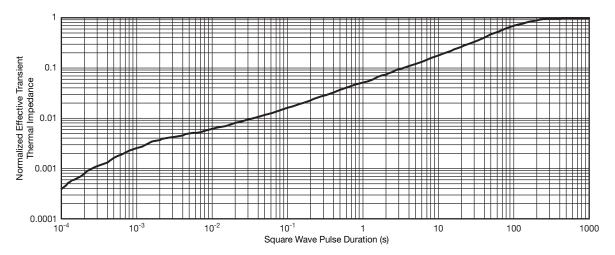
**Drain Source Breakdown vs. Junction Temperature** 



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



#### Safe Operating Area

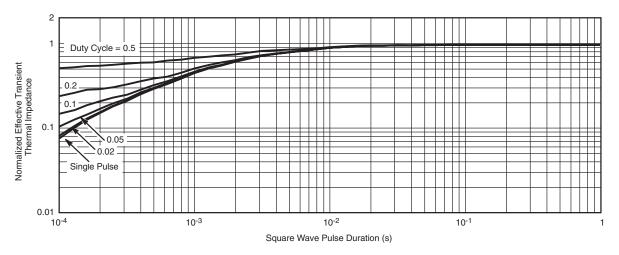


Normalized Thermal Transient Impedance, Junction-to-Ambient

5



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



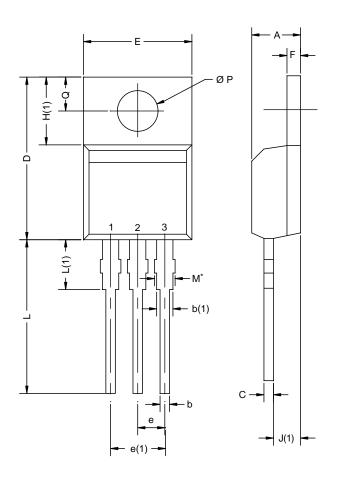
#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

# **TO-220AB**



	MILLIN	METERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.25	4.65	0.167	0.183		
b	0.69	1.01	0.027	0.040		
b(1)	1.20	1.73	0.047	0.068		
С	0.36	0.61	0.014	0.024		
D	14.85	15.49	0.585	0.610		
E	10.04	10.51	0.395	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.09	6.48	0.240	0.255		
J(1)	2.41	2.92	0.095	0.115		
L	13.35	14.02	0.526	0.552		
L(1)	3.32	3.82	0.131	0.150		
ØΡ	3.54	3.94	0.139	0.155		
Q	2.60	3.00	0.102	0.118		
ECN: X12-0208-Rev. N, 08-Oct-12						

DWG: 5471

### Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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